

Heat Sink for NVIDIA® Jetson AGX Xavier™ / AGX Orin™



ATS Part#: **ATS-NVA-3275-C4-R0**

Description: 100 x 87 x 16 mm high-performance active heat sink with screw attachment

Component: NVIDIA Jetson AGX Xavier & AGX Orin Modules

Heat Sink Type: Active heat sink (fan not included)

Heat Sink Attachment: Stainless steel screw



Image for illustration purposes only.

Features & Benefits

- » Designed to fit the NVIDIA® Jetson AGX Xavier™ and AGX Orin™ modules
- » Cooling capacity up to 60W
- » Stainless steel screw fan attachment ensures dependable long-term fan to heat sink assembly
- » Fan assembly hole pattern is 71.5 mm C-C (center to center) - see Fig. 1
- » Included fan assembly kit: ATS-HK507-R0 (PPH, 4-40 X 1 3/8" screws with standoffs)
- » Fan not included - ATS recommended fans listed below
- » Provided with pre-assembled Thermal Interface Material (TIM) on base
- » Mounting Screws - M3x0.5 (3mm standard) - Thread length: 30
- » Recommended through hole size in PCB is 3.40 mm

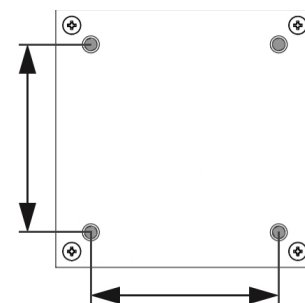


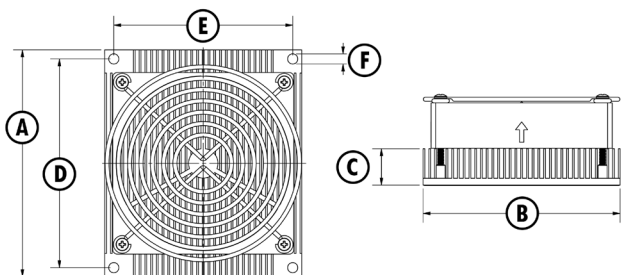
Fig. 1 - Measured dimensions of fan assembly hole pattern

Heat Sink Part Number	L (mm)	W (mm)	H (mm)	Thermal Resistance (°C/W)	Heat Sink Weight (g)	Thermal Interface Material
ATS-NVA-3275-C4-R0	100	87	16	0.21	164.3	Chomerics T766

Recommended Fans

Part Number	Manufacturer	L (mm)	W (mm)	H (mm)	Voltage (VDC)	Air Flow (CFM)	Static Pressure (Pa)	Lead Wire
9GA0812P6G001	Sanyo Denki	80	80	20	12	60.8 (1.70m³/min)	109.6	Red (+) Yellow (Sensor) Black (-) Brown (Control)
AFB0812VHD-A	Delta	80	80	20	12	63.5 (1.78m³/min)	98.1	Black (-), Red (+)

Product Details

SCHEMATIC IMAGE	Dimension A	Dimension B	Dimension C	Dimension D	Dimension E	Dimension F	Material	Finish
	100 mm	87 mm	16 mm	92 mm	79 mm	4.5 mm	Aluminum 6063	Black Anodized

NOTES:

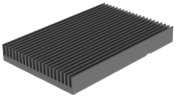
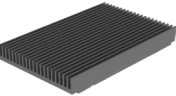
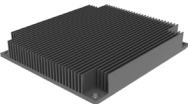
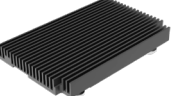
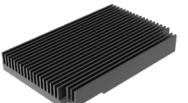
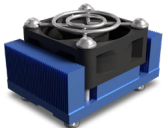
- 1) Fan not included. Fan type is specific to individual customer requirements and needs to be independently sourced.
- 2) Dimensions A and B refer to heat sink size.
- 3) Dimension C is the heat sink height from the bottom of the base to the top of the fin field.
- 4) Dimensions D and E refer to the mounting hole pattern C-C (center to center)
- 5) Dimension F refers to the mounting hole diameter
- 6) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 7) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 8) ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.
- 9) Contact ATS to learn about custom options available.

*All Images are for illustration purposes only.



Heat Sinks for NVIDIA® Jetson™ Products



	NVIDIA Product	Heat Sink Part Number	L (mm)	W (mm)	H (mm)	Weight (g)	Thermal Resistance (°C/W at 200 LFM / 1 M/S)
	Jetson Nano™	ATS-NVA-2780-C1-R0	60	40	8	35.5	2.2
		ATS-NVP-2780-C2-R0	60	40	8	32.3	3.24
	Jetson Xavier™ NX	ATS-NVA-2781-C1-R0	60	40	8	36.8	1.6
		ATS-NVP-2781-C2-R0	60	40	8	34.2	2.55
	Jetson AGX Xavier™ Jetson AGX Orin™	ATS-NVA-3275-C4-R0	100	87	16	164.3	0.21
		ATS-NVP-3275-C5-R0	100	87	16	167.7	0.53
	Jetson Orin™ Nano Jetson Orin™ NX	ATS-NVA-3281-C1-R1	63	40	8	38.3	1.6
		ATS-NVP-3281-C2-R1	63	40	8	36.2	2.45
	Jetson™ TX2 NX	ATS-NVA-3353-C1-R2	63	40	8	37.4	1.7
		ATS-NVP-3353-C2-R2	63	40	8	34.3	2.57
	Jetson Orin™ NX (Super Mode)	ATS-NVA2-3554-C3-R0	57.5	40	23	56	0.94

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